



Material Content Data Sheet



Sales Product Name	TLE4253E			Issued	25. January 2018			
MA#	MA001674350							
Package	PG-DSO-8-27			Weight*	84.26 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.205	2.62	2.62	26164	26164
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8636	
wire	non noble metal	copper	7440-50-8	29.548	35.07	35.98	350655	359831
	noble metal	gold	7440-57-5	0.090	0.11	0.11	1069	1069
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1162
plastics	plastics	epoxy resin	-	4.503	5.34		53434	
	inorganic material	silicondioxide	60676-86-0	44.340	52.62	58.08	526210	580806
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8249	8249
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8598	8598
glue	plastics	epoxy resin	-	0.322	0.38		3821	
	noble metal	silver	7440-22-4	0.966	1.15	1.53	11462	15283
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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